

L2	14	1 and etching and grinding	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/05 17:21
L3	45	1 and (conductive near1 (adhesive paste))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/05 17:31
L4	154	(chip die) with (bonding bonded) with (substrate board) with (conductive near1 paste)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/05 17:32
L5	89	4 and (bump ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/05 17:32
L6	10	5 and (adhesive near (film tape))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/05 17:35
L7	79	5 not 6	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/05 17:40